

ABSTRACT OF THE DISCLOSURE

A structure useful as a probe for testing electrical interconnections to integrated circuit devices and other electronic components having a substrate

with a bond wire elongated electrical conductor extending away from the surface of the substrate. Each of the bond wire elongated electrical conductors has a first end affixed to the surface at an electrical contact location and a multitude of second ends projecting away from the surface. The first end and said second end of bond wire elongated electrical connector has a ball-shaped protuberance positioned thereon and there exists a in the system means for permitting each of the second ends to move about reference positions.

The element which contains means for permitting each of the second ends to move about reference positions is a sheet of material having a plurality of through-holes therein through which the second ends project. There is a perforation in each said sheet in the vicinity of said openings. —